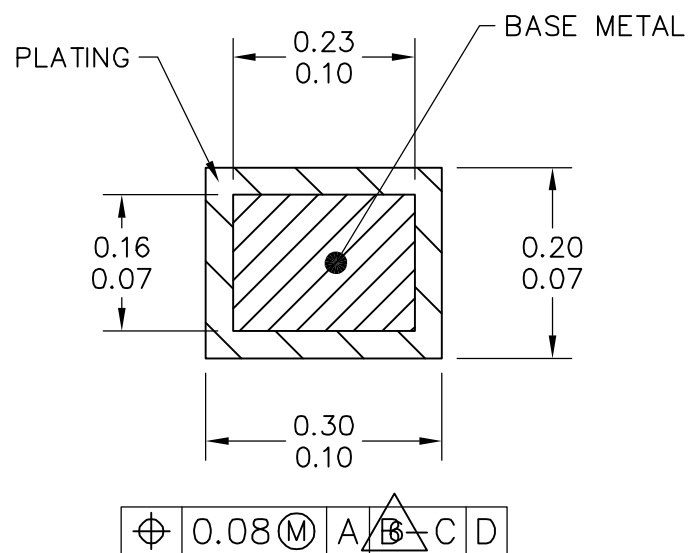
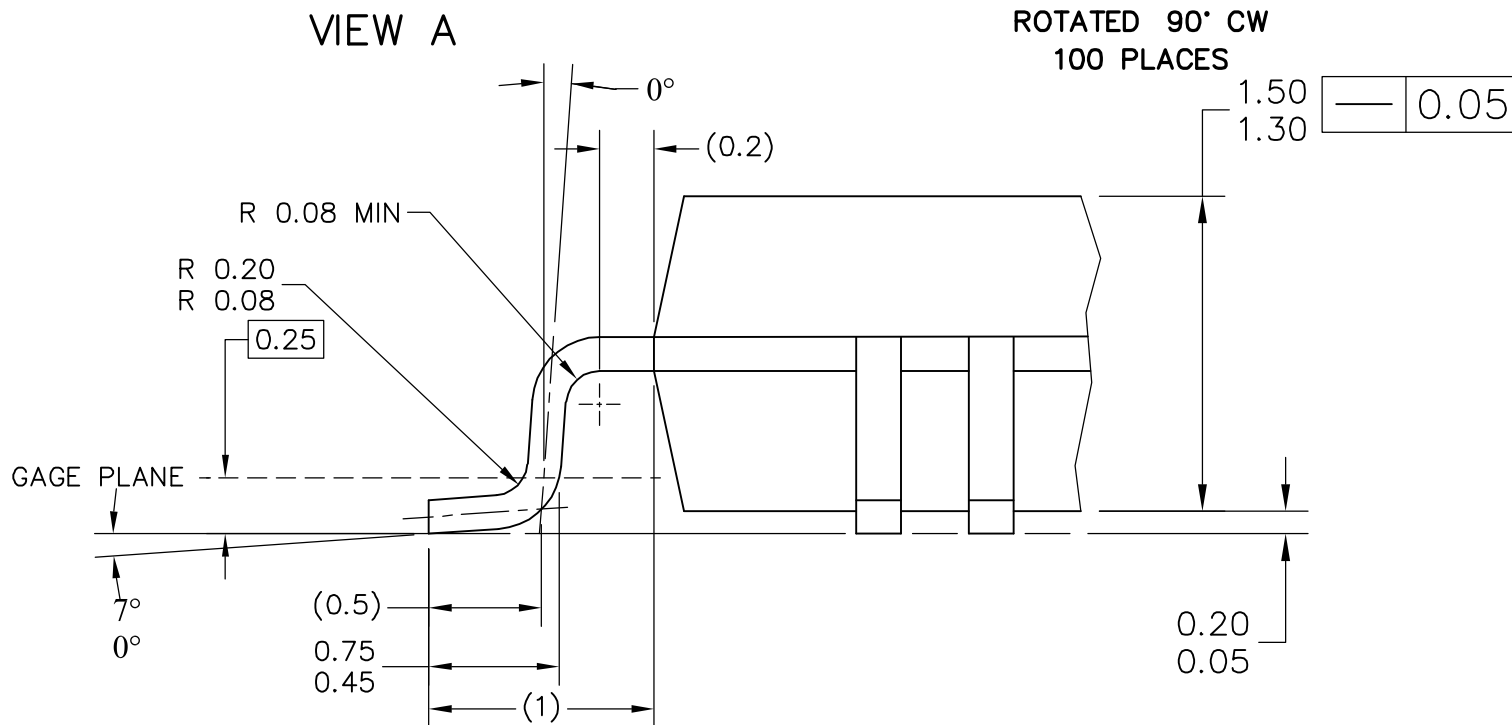


SIDE VIEW

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TITLE: 100 LEAD LQFP 14 X 14, 0.5 PITCH, 1.4 THICK			DOCUMENT NO: 98ASS23308W		REV: J
			CASE NUMBER: 983-02		30 JUN 2010
			STANDARD: NON-JEDEC		



ROTATED 90° CW
100 PLACES



VIEW B

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			CASE NUMBER: 983-02		30 JUN 2010
			STANDARD: NON-JEDEC		



NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.

2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M–1994.

3. DATUMS B, C AND D TO BE DETERMINED AT DATUM PLANE H.

4. THE TOP PACKAGE BODY SIZE MAY BE SMALLER THAN THE BOTTOM PACKAGE SIZE BY A MAXIMUM OF 0.1 MM.

5. DIMENSIONS DO NOT INCLUDE MOLD PROTRUSIONS. THE MAXIMUM ALLOWABLE PROTRUSION IS 0.25 mm PER SIDE. THE DIMENSIONS ARE MAXIMUM BODY SIZE DIMENSIONS INCLUDING MOLD MISMATCH.

6. DIMENSION DOES NOT INCLUDE DAM BAR PROTRUSION. PROTRUSIONS SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED 0.35. MINIMUM SPACE BETWEEN PROTRUSION AND AN ADJACENT LEAD SHALL BE 0.07 MM.

7. DIMENSIONS ARE DETERMINED AT THE SEATING PLANE, DATUM A.

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